

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claim 1 (currently amended): A supporting device for an integrated circuit package having a column grid array interconnection with a printed circuit board, said supporting device comprising:

a shim that is inserted between the integrated circuit package and the printed circuit board,

wherein said shim is mechanically and removably fastened to the printed circuit board and wherein said shim has a Y shape.

Claim 2 (original): The supporting device of claim 1, wherein the shim comprises an extrusion that is inserted between the integrated circuit package and the printed circuit board, and a base that comprises a fastening means to secure the shim to the printed circuit board.

Claim 3 (previously presented): The supporting device of claim 2, wherein the base and the extrusion are shaped to prevent the extrusion from coming into contact with a solder column of the integrated circuit package.

Claim 4 (original): The supporting device of claim 3, wherein the extrusion is designed to provide a gap between the extrusion and the integrated circuit package immediately after the installation of the supporting device.

Claim 5 (original): The supporting device of claim 1, wherein the supporting device is installed on a corner of the integrated circuit package.

Claim 6 (canceled).

Claim 7 (original): The supporting device of claim 1, wherein the supporting device is made of a material having a coefficient of thermal expansion that matches coefficients of thermal expansion of solder columns of the integrated circuit package.

Claim 8 (previously presented): The supporting device of claim 2, wherein the fastening means is a screw.

Claim 9 (previously presented): The supporting device of claim 2, wherein the fastening means is a dimple.

Claim 10 (currently amended): A method for mechanically supporting an integrated circuit package having a column grid array interconnection with a printed circuit board, said method comprising:

inserting one or more supporting devices between the integrated circuit package and the printed circuit board; and

mechanically and removably fastening the one or more supporting devices to the printed circuit board, wherein the one or more supporting devices have a Y shape.

Claim 11 (previously presented): The method of claim 10, wherein the inserting inserts one or more supporting devices between the integrated circuit package and the printed circuit board after the integrated circuit package is solder attached to the printed circuit board.

Claim 12 (previously presented): The method of claim 11, wherein the inserting positions the one or more supporting devices so that there is a gap between a top surface of the one or more supporting devices and an under surface of the integrated circuit package.

Claim 13 (original): The method of claim 10, wherein the fastening fastens the one or more supporting devices on one or more corners of the integrated circuit package.

Claim 14 (previously presented): The method of claim 10, wherein the fastening fastens the one or more supporting devices to the printed circuit board by screws.

Claim 15 (previously presented): The method of claim 10, wherein the fastening fastens the one or more supporting devices to the printed circuit board by dimples.

Claim 16 (new): A supporting device comprising:

a shim that is inserted between an integrated circuit package and a printed circuit board, wherein the shim is mechanically and removably fastened to the printed circuit board and wherein the shim is installed on a corner portion of the integrated circuit package.

Claim 17 (new): The supporting device of claim 16, wherein the shim comprises an extrusion that is inserted between the integrated circuit package and the printed circuit board, and a base that comprises a fastening means to secure the shim to the printed circuit board.

Claim 18 (new): The supporting device of claim 17, wherein the extrusion is designed to provide a gap between the extrusion and the integrated circuit package immediately after the installation of the supporting device.

Claim 19 (new): The supporting device of claim 16, wherein the shim has a Y shape.

Claim 20 (new): The supporting device of claim 16, wherein the fastening means is a screw.